

Innogration (Suzhou) Co., Ltd.

Document Number: STBH15065A2C Preliminary Datasheet V1.0

GaN HEMT 28V, HF-1.5GHz 65W, RF Power Transistor Description

The STBH15065A2C is a 65W GaN HEMT, designed for multiple applications up to 1.5GHz It can be used in CW, Pulse and any other modulation modes. There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.



Typical class AB RF Performance with device soldered

Vds=28V, Idq=100mA, CW

Freq	P1dB	P1dB	P1dB	P1dB	P3dB	P3dB	P3dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
650	47.7	58.9	64.2	18.41	48.15	65.2	66.6
700	47.88	61.4	63.5	19.1	48.33	68.1	64.8
750	47.45	55.7	58.3	18.64	48.03	63.6	60.0
800	47.52	56.5	57.3	18.74	48.55	71.6	63.7
830	48.22	66.3	63.1	18.58	49	79.5	68.5
860	48.56	71.9	67.0	18.06	49.13	81.9	70.5

Applications

- L band power amplifier
- P band power amplifier
- ISM/RF Energy power amplifier

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

- 1. Set VGS to the pinch--off (VP) voltage, typically -5 V
- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

Turning the device OFF

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Table 1. Maximum Ratings

· uare · · · · · · · · · · · · · · · · · · ·					
Rating	Symbol	Value	Unit		
DrainSource Voltage	V _{DSS}	+200	Vdc		
GateSource Voltage	V _{GS}	-8 to +0.5	Vdc		
Operating Voltage	V _{DD}	50	Vdc		
Maximum gate current	lgs	16.8	mA		
Storage Temperature Range	Tstg	-65 to +150	°C		
Case Operating Temperature	T _C	+150	°C		
Operating Junction Temperature	TJ	+225	°C		

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA	RеJC	2.0	°C /W
T _C = 85°C, at Pdiss=30W		2.8	-C/VV

Innogration (Suzhou) Co., Ltd.

Document Number: STBH15065A2C Preliminary Datasheet V1.0

Table 3. Electrical Characteristics (TA = 25° C unless otherwise noted)

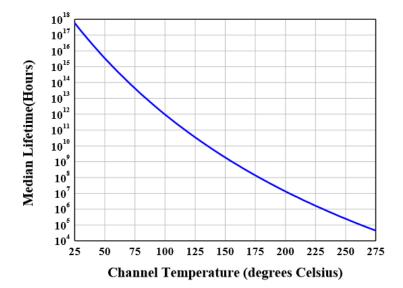
DC Characteristics (measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=16.8mA	V _{DSS}		200		V
Gate Threshold Voltage	VDS =10V, ID = 16.8mA	$V_{GS(th)}$	-4		-2	V
Gate Quiescent Voltage	VDS =28V, IDS=100mA, Measured in Functional Test	$V_{GS(Q)}$		-3.3		V

Ruggedness Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	1.5GHz, Pout=65W Pulsed CW					
	All phase,	VSWR		10:1		
	No device damages					

Figure 2: Median Lifetime vs. Channel Temperature



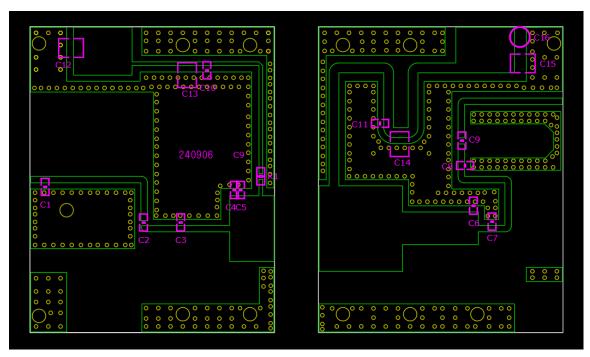
Document Number: STBH15065A2C Preliminary Datasheet V1.0

650-860MHz Typical performance

Figure 3: Network analyzer output S11/S21



Figure 4: Picture of application board





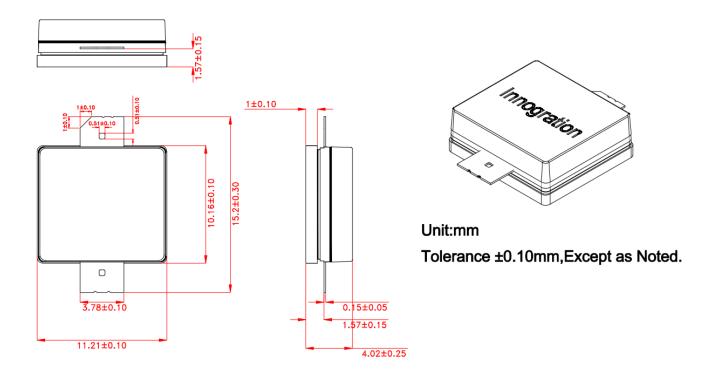
Innogration (Suzhou) Co., Ltd.

Document Number: STBH15065A2C Preliminary Datasheet V1.0

Reference	Footprint	Value	Quantity
C1,	0805	2.4pF	1
C2	0805	36pF	1
C3	0805	15pF	1
C4	0805	6.8pF	1
C5	0805	15pF	1
C6	0805	2.2pF	1
C7	0805	0.3pF	1
C8	0805	3pF	1
C9、C10、C11	0805	120pF	3
C12、C13、C14、C15	1210	10uF/63V	4
C16		470uF/63V	1
R1	0603	10ohm	1
PCB	RO4350B	20mils	

Document Number: STBH15065A2C Preliminary Datasheet V1.0

Package Dimensions (Unit:mm)



Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2025/4/17	V1.0	Preliminary Datasheet Creation
_		

Application data based on: ZYX-25-09

Notice

Specifications are subject to change without notice. Innogration believes the information within the data sheet to be reliable. Innogration makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose.

"Typical" parameter is the average values expected by Innogration in quantities and are provided for information purposes only. It can and do vary in different applications and related performance can vary over time. All parameters should be validated by customer's technical experts for each application.

Innogration products are not designed, intended or authorized for use as components in applications intended for surgical implant into the body or to support or sustain life, in applications in which the failure of the Innogration product could result in personal injury or death or in applications for planning, construction, maintenance or direct operation of a nuclear facility.

For any concerns or questions related to terms or conditions, please check with Innogration and authorized distributors Copyright © by Innogration (Suzhou) Co.,Ltd.